GOMACTech–17 CONFERENCE SCHEDULE

GRAND SIERRA RESORT, RENO, NEVADA — 19–23 MARCH 2017

	GOMACTech Timetable	Grand Ballroom Foyer	Grand Ballroom	Carson Room	Carson 1	Carson 2	Carson 3	Carson 4	GOMACTech Timetable	
Sunday, 19 March	5:00–8:00 pm	**Registration**	**Networking Reception** (6:00-8:00 pm)	....	....	....	....	....	5:00–8:00 pm	Sunday, 19 March
Monday, 20 March	8:30–12:00 pm	**Registration** (7:00–5:00 pm)	....		....	....	**Special Session 1** Trusted Suppliers Industry Day	....	8:30–12:00 pm	Monday, 20 March
	LUNCH 12:00–1:00 pm		....	....	LUNCH	....	LUNCH	....	LUNCH 12:00–1:00 pm	
	1:00–5:00 pm		....	....	**Special Session 2** Introduction to Superconducting Electronics	....	**Special Session 1** Trusted Suppliers Industry Day	....	1:00–5:00 pm	
Tuesday, 21 March	8:30–9:45 am	**Registration** (7:00–5:00 pm)	....	**Plenary Session** Introductory Remarks Awards Keynote Address	....	....	....	....	8:30–9:45 am	Tuesday, 21 March
	BREAK 9:45–10:15 am		....	**BREAK (Carson Room)**				....	BREAK 9:45–10:15 am	
	10:15–11:45 am		....	**Kilby Lectures**	....	....	....	....	10:15–11:45 am	
	LUNCH 11:45 am–1:30 pm		....	**LUNCH (Grand Ballroom)**				....	LUNCH 11:45 am–1:30 pm	
	1:30–3:00 pm		**Exhibits** (12:00–8:00 pm)	....	**Session 1** Physical/ Functional Analysis	**Session 2** Millimeter-Wave GaN Power Amplifiers	**Session 3** Near-Zero Power RF and Sensor Operations (DARPA N-ZERO) I	**Session 4** Advanced Packaging Technologies	1:30–3:00 pm	
	BREAK 3:00–3:30 pm			....	**BREAK (Grand Ballroom)**				BREAK 3:00–3:30 pm	
	3:30–5:10 pm			....	**Session 5** Verification and Validation	**Session 6** Phased Array	**Session 7** Near-Zero Power RF and Sensor Operations (DARPA N-ZERO) II	**Session 8** Beyond CMOS Technologies	3:30–5:10 pm	
	6:00–8:00 pm	....		**EXHIBITOR RECEPTION (Grand Ballroom)**					6:00–8:00 pm	
Wednesday, 22 March	8:20–10:00 am	**Registration** (7:00–5:00 pm)	**Exhibits** (9:00–4:00 pm)	....	**Session 9** FPGA Security	**Session 10** GaN Amplifiers	**Session 11** Circuit Realization at Faster Time Scales (DARPA CRAFT)	**Session 12** Radiation-Hardened Technologies and Processes	8:20–10:00 am	Wednesday, 22 March
	BREAK 10:00–10:30 am			....	**BREAK (Grand Ballroom)**				BREAK 10:00–10:30 am	
	10:30–12:00 pm			....	**Session 13** Thermal Management for High-Performance Computing (DARPA Ice Cool) I	**Session 14** DARPA Arrays at Commercial Time Scales (ACT)	**Session 15** Diamond Electronics	**Session 16** Neuromorphic Comp	10:30–12:00 pm	
	LUNCH 12:00–1:30 pm			....	**LUNCH (Grand Ballroom)**				LUNCH 12:00–1:30 pm	
	1:30–3:00 pm			....	**Session 17** Thermal Management of GAN Power Amplifiers (DARPA Ice Cool) II	**Session 18** Reconfigurable Electronics for Agile Multi-Function RF	**Session 19** Optical Interconnects	**Session 20** Quantum Sensing and Information Technologies	1:30–3:00 pm	
	BREAK 3:00–3:30 pm			....	**BREAK (Grand Ballroom)**				BREAK 3:00–3:30 pm	
	3:30–5:10 pm		....	....	**Session 21** Vanishing Programmable Electronics (DARPA VAPR)	**Session 22** RF Photonics	**Session 23** Advanced Power Electronics	**Session 24** Radiation-Hardened Design and Characterization Methods	3:30–5:10 pm	
	7:00–10:00 pm	....	....	**WEDNESDAY EVENING SOCIAL (Nevada Museum of Art)**					7:00–10:00 pm	
Thursday, 23 March	8:20–10:00 am	**Registration** (7:00–3:00 pm)	....	....	**Session 25** Component Authentication and ID	**Session 26** GaN Power Electronics	**Session 27** Advanced Materials and Enabling Technology	**Session 28** Superconducting Technologies	8:20–10:00 am	Thursday, 23 March
	BREAK 10:00–10:30 am		....	....	**BREAK (Grand Ballroom)**				BREAK 10:00–10:30 am	
	10:30–12:00 pm		**Poster Session**	....	....	....	....	....	10:30–12:00 pm	
	LUNCH 12:00–1:30 pm		....	....	**LUNCH (Grand Ballroom)**				LUNCH 12:00–1:30 pm	
	1:30–3:00 pm		....	....	**Session 29** Obfuscation	**Session 30** Passive RF Components	**Session 31** Diverse Accessible Heterogeneous	**Session 32** EO Sensing Components & Technologies	1:30–3:00 pm	
	BREAK 3:00–3:30 pm	....	....	....	**BREAK (Grand Ballroom)**				BREAK 3:00–3:30 pm	
	3:30–5:00 pm	....	....	....	**Session 33** Secure Architectures and Systems	**Session 34** Advanced Analog-to-Digital Converters	**Session 35** Ultra-Wide-Band-Gap Semiconductors	**Session 36** Radiation-Hardened Processing and Systems	3:30–5:00 pm	